

AMENDMENTS TO THE CLAIMS:

Complete Listing of Claims

- 1 1. (currently amended) An encapsulated transponder chip assembly
2 comprising:
3 a flexible baseplate (12),
4 a transponder chip (10) attached to the baseplate in such a way that its
5 contact surfaces (20) face away from the baseplate (12),
6 a layer (14) of a conductive material applied to the baseplate (12) and
7 arranged to around the transponder chip to form an aerial occupying a relatively
8 large surface area as compared with the transponder chip so as to provide
9 pressure-relief for the transponder chip (10), and having a support surface facing
10 away from the baseplate (12) which is at least as high as the surface of the chip
11 (10) facing away from the baseplate,
12 a flexible cover plate (16) arranged on the layer of conductive material
13 (14), whose one side, opposing the chip (10), being provided with one or more
14 conductive surfaces (18), which are arranged in such a way that they form an
15 electrical connection between the chip (10) and the layer of conductive material
16 (14), the support surface of the layer (14) serving as a support for the cover plate
17 (16).
- 1 2. (original) The encapsulated chip according to claim 1, whereby the chip (10)
2 is surrounded by a filler material that fills the open space between the baseplate
3 (12) and the cover plate (16).
- 1 3. (original) The encapsulated chip according to claim 2, further comprising an
2 electrically conductive glue, which is to establish both the electrical and the

3 mechanical connections between the contact surfaces (20) of the chip (10) and
4 the conductive surface (18) or the conductive surfaces (18), respectively, of the
5 cover plate (16).

1 4. (original) The encapsulated chip according to claim 2, further comprising an
2 anisotropically conductive film (26) (ACF), which serves to establish both an
3 electrical and a mechanical connection between the contact surfaces (20) of the
4 chip (10) and the conductive surface (18) or the conductive surfaces (18),
5 respectively, of the cover plate (16), and between the conductive surface (18) or
6 the conductive surfaces (18), respectively, of the cover plate (16) and the
7 conductive layer (14) applied to the baseplate (12).

1 5. (original) The encapsulated chip according to claim 4, whereby the filler
2 material consists of the anisotropically conductive film (26).

Claim 6. (canceled)

1 7. (original) The encapsulated chip according to claim 1, where the height of the
2 chip (10) is so low that it is rendered flexible.

1 8. (previously presented) The encapsulated chip according to claim 7, where
2 the chip (10) consists mainly of silicon and has a thickness of less than 50 μm .

1 9. (original) The encapsulated chip according to claim 1, where the chip (10)
2 comprises a transponder.

Claims 10-15. (canceled)